

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. ....09/468,247  
 Priority Filing Date .....12/20/99  
 Inventor.....Perino et al.  
 Applicant ..... Rambus, Inc.  
 Priority Group Art Unit .....2833  
 Priority Examiner ..... Paumen  
 Attorney's Docket No. .... RB1-035USC3  
 Title: Chip Socket Assembly and Chip File Assembly for Semiconductor Chips

**PRELIMINARY AMENDMENT**

To: Commissioner of Patents and Trademarks,  
Washington, D.C. 20231

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**AMENDMENTS****In the Specification:**

On page 2, prior to the heading "FIELD OF THE INVENTION", please  
insert the following:

**--RELATED APPLICATIONS**

This is a continuation of U.S. Patent Application Serial No. 09/468,247,  
filed December 20, 1999, which is now U.S. Patent No. ....--

**In the Claims:**

Please cancel claims 1-67.

Please add the following new claims 68-90.

1       **68.**    A chip package comprising:

2       packaging material having a first side and a second side,

3       a lead extending from the first side of the packaging material, and

4       a first clip portion extending from a second side of the packaging material.

5  
6       **69.**    The chip package of claim 68, further comprising a second clip  
7       portion extending from a third side of the packaging material.

8  
9       **70.**    The chip package of claim 69, further comprising a flexible insert  
10       residing between the lead and the first side of the packaging material, wherein the  
11       flexible insert supplies spring force when the lead is compressed.

12  
13       **71.**    The chip package of claim 70, wherein the flexible insert is  
14       cylindrical.

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16       **72.**    The chip package of claim 71, wherein the flexible insert is a  
17       compliant material.

18  
19       **73.**    The chip package of claim 72, wherein the compliant material is an  
20       elastomer.

21  
22       **74.**    The chip package of claim 70, wherein the lead is substantially C-  
23       shaped.

1           **75.**    The chip package of claim 74, wherein the lead is compressible.

2  
3           **76.**    The chip package of claim 70, wherein the lead is compressible.

4  
5           **77.**    The chip package of claim 68, further comprising a support pin  
6 extending from the packaging material.

7  
8           **78.**    The chip package of claim 69, wherein the first and second clip  
9 portions are integral with the packaging material.

10  
11          **79.**    The chip package of claim 68, wherein the lead is a flexible metallic  
12 material.

13  
14          **80.**    The chip package of claim 78, wherein the metallic material  
15 comprises beryllium-copper.

16  
17          **81.**    The chip package of claim 68, wherein the packaging material is  
18 comprised of a flexible material.

19  
20          **82.**    The chip package of claim 81, wherein the flexible material supplies  
21 spring force when the lead is compressed.

22  
23          **83.**    The chip package of claim 68, wherein the packaging material  
24 comprises silicone rubber.

1           **84.**   The chip package of claim 68, further comprising a cam follower  
2 extending from the packaging material.

3  
4           **85.**   The chip package of claim 68, further comprising an integrated  
5 circuit disposed in the packaging material.

6  
7           **86.**   The chip package of claim 69, wherein the first and second clip  
8 portions are flexible.

9  
10          **87.**   The chip package of claim 68, wherein the packaging material has a  
11 bottom-facing housing that extends laterally from the packaging material, the  
12 bottom-facing housing having a pocket formed therein.

13  
14          **88.**   The chip package of claim 87, wherein an end of the lead is disposed  
15 within  
16 the pocket when the lead is compressed.

17  
18          **89.**   A package, comprising:  
19 an integrated circuit enclosed with the package,  
20 substantially C-shaped leads at a first end of the package,  
21 a guide member on a side of the package, wherein the guide member has a  
22 ramp, and  
23 mechanical support pins at a second end of the package opposite the first  
24 end,  
25

1 wherein the package resides substantially horizontally with respect to a  
2 circuit board when the package is inserted in a base assembly coupled to the circuit  
3 board.  
4

5 **90.** The package of claim 89, wherein the integrated circuit is a dynamic  
6 random access memory device.  
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9  
10 Respectfully Submitted,

11  
12 Date: 9/20/01

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